

1A, 200V Ultra Fast Surface Mount Rectifier

FEATURES

- Very low profile - typical height of 0.68mm
- Reduce switching and conduction loss
- Ideal for automated placement
- Ultra fast recovery times for high frequency
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- DC to DC converter
- Switching mode converters and inverters
- Freewheeling application

MECHANICAL DATA

- Case: Micro SMA
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.006g (approximately)

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
I_F	1	A
V_{RRM}	200	V
I_{FSM}	15	A
T_{JMAX}	150	°C
Package	Micro SMA	
Configuration	Single die	



Micro SMA



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)			
PARAMETER	SYMBOL	ESH1DM	UNIT
Marking code on the device		D3	
Repetitive peak reverse voltage	V_{RRM}	200	V
Reverse voltage, total rms value	$V_{R(RMS)}$	140	V
Forward current	I_F	1	A
Surge peak forward current, 8.3ms single half sine wave superimposed on rated load	I_{FSM}	15	A
Junction temperature	T_J	-55 to +150	°C
Storage temperature	T_{STG}	-55 to +150	°C

THERMAL PERFORMANCE			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance	$R_{\theta JL}$	40	°C/W
Junction-to-ambient thermal resistance	$R_{\theta JA}$	92	°C/W

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ\text{C}$ unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage ⁽¹⁾	$I_F = 1\text{A}, T_J = 25^\circ\text{C}$	V_F	1.25	1.50	V
Reverse current @ rated V_R ⁽²⁾	$T_J = 25^\circ\text{C}$	I_R	-	1	μA
	$T_J = 125^\circ\text{C}$		-	50	μA
Junction capacitance	1MHz, $V_R = 4.0\text{V}$	C_J	3	-	pF
Reverse recovery time	$I_F = 0.5\text{A}, I_R = 1.0\text{A}$ $I_{rr} = 0.25\text{A}$	t_{rr}	-	25	ns

Notes:

1. Pulse test with $PW = 0.3\text{ms}$
2. Pulse test with $PW = 30\text{ms}$

ORDERING INFORMATION		
ORDERING CODE	PACKAGE	PACKING
ESH1DM	Micro SMA	12,000 / Tape & Reel

CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

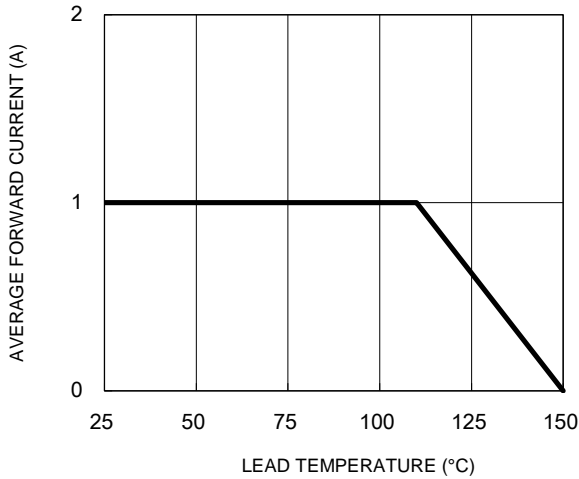


Fig.2 Maximum Non-Repetitive Forward Surge Current

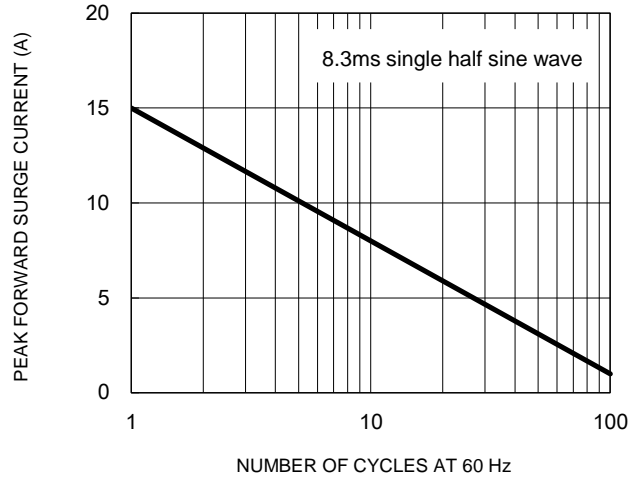


Fig.3 Typical Reverse Characteristics

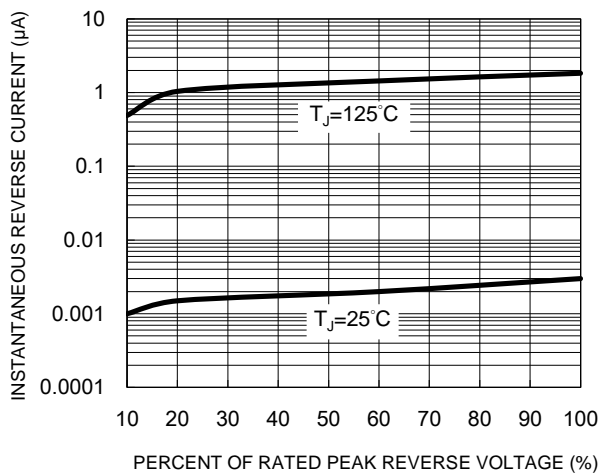


Fig.4 Typical Forward Characteristics

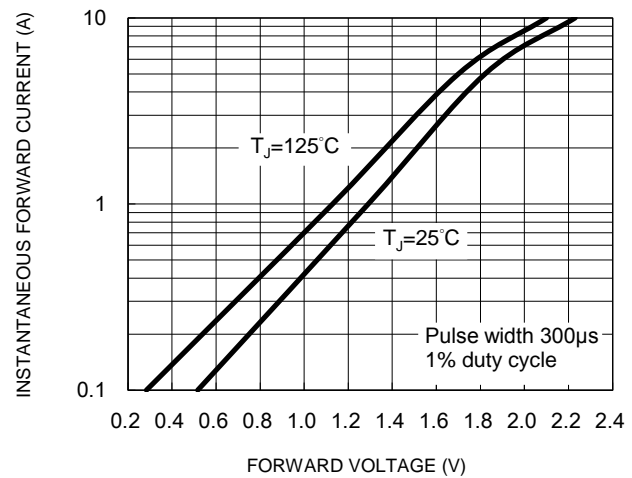
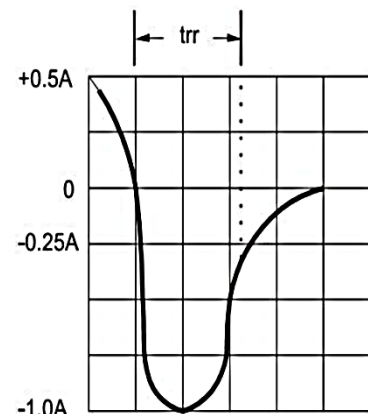
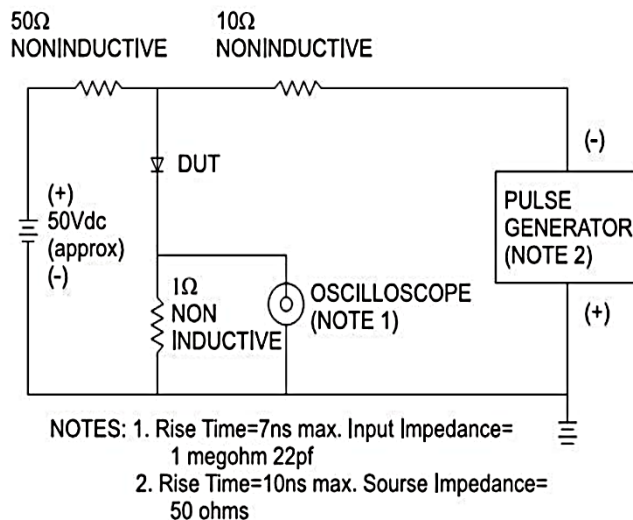
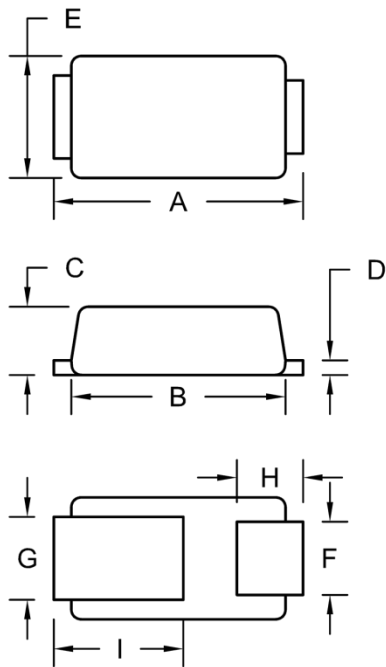


Fig.5 Reverse Recovery Time Characteristic and Test Circuit Diagram



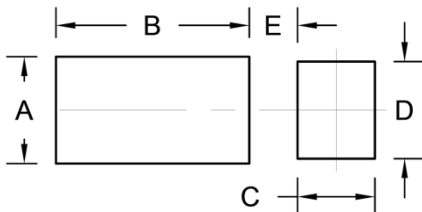
PACKAGE OUTLINE DIMENSIONS

Micro SMA



DIM.	Unit (mm)		Unit (inch)	
	Min.	Max.	Min.	Max.
A	2.30	2.70	0.091	0.106
B	2.10	2.30	0.083	0.091
C	0.63	0.73	0.025	0.029
D	0.10	0.20	0.004	0.008
E	1.15	1.35	0.045	0.053
F	0.65	0.85	0.026	0.034
G	0.75	0.95	0.030	0.037
H	0.55	0.75	0.022	0.030
I	1.10	1.50	0.043	0.059

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	1.10	0.043
B	2.00	0.079
C	0.80	0.031
D	1.00	0.039
E	0.50	0.020

Notes:

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met.

MARKING DIAGRAM



P/N = Marking Code
YW = Data Code

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